

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : SSB0-ZZ-0010

Description : SFP+ 2X2 Ass'y

Press-Fit

Contact Area : 30μ" Min. Gold

With LightPipe

Packing With Tray



Spec No.
SSB021011-00

Update Date
2021/6/7

Revision
A

Approved	Checked	Prepared



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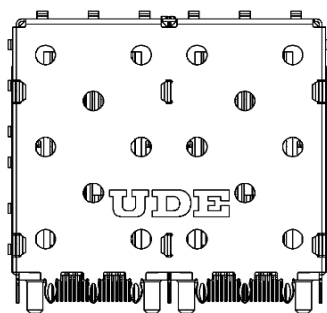
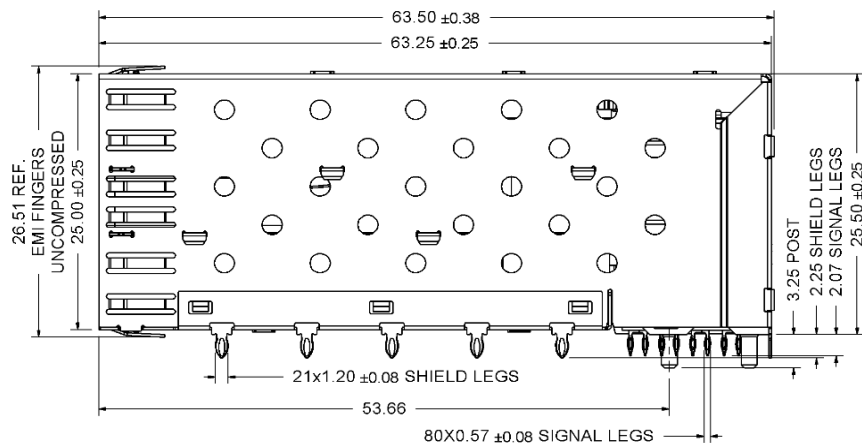
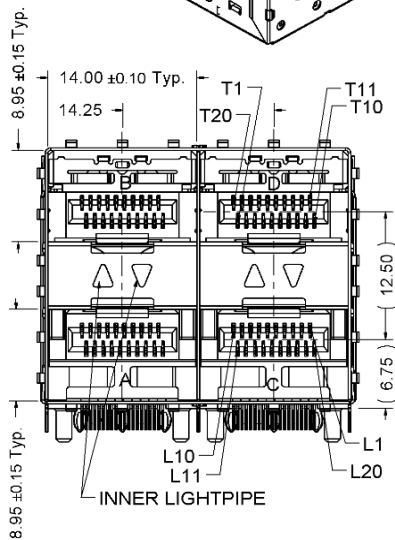
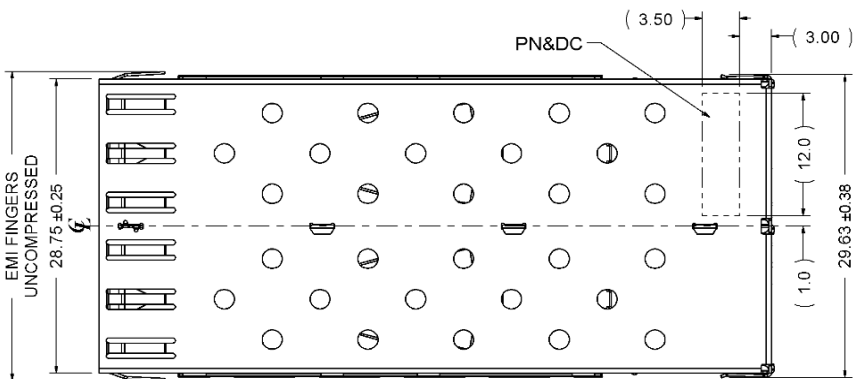
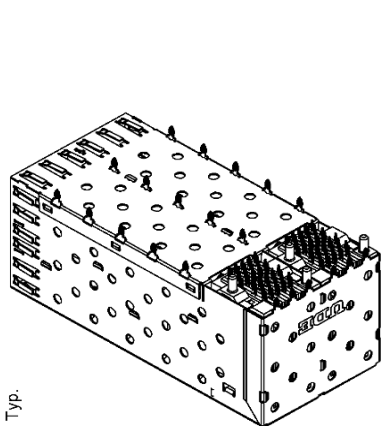
Revision History

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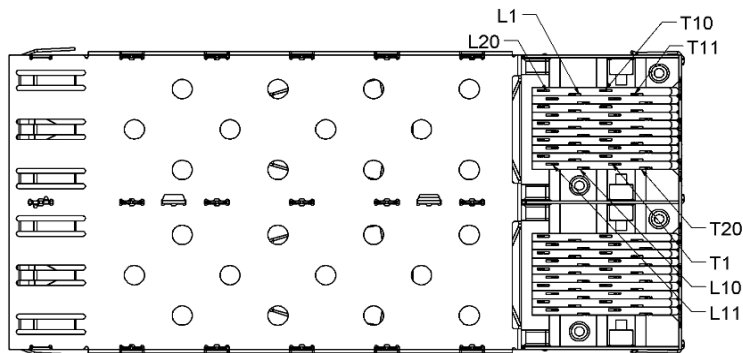
1. MECHANICAL DIMENSION

Product Dimension

Unit:mm	General Tolerance :	X.X : ± 0.38
		X.XX : ± 0.20



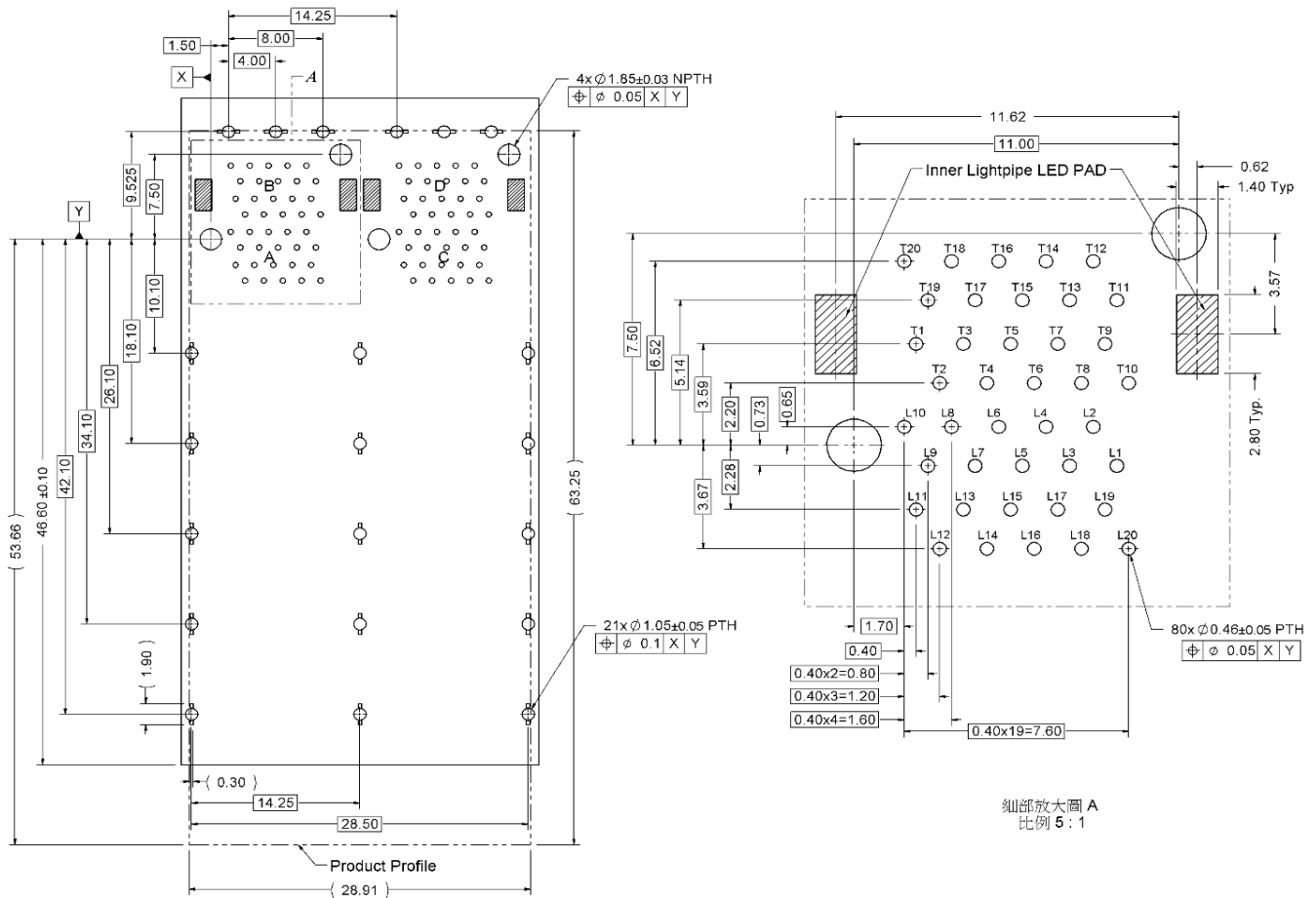
RIGHT VIEW



2. Recommended PCB Layout.Component Side of Board

All dimension units are "mm".

All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified

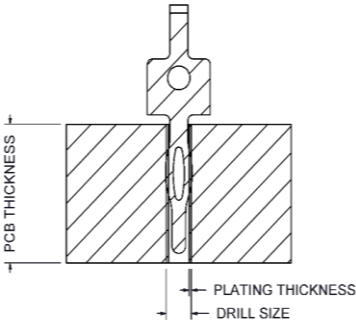


NOTES:

- 1.RECOMMENDED THRU HOLE PLATING INCLUDES HASL,OSP,OR IMMERSION(GOLD,SILVER,OR TIN)
- 2.1.57mm MINIMUM PCB THICKNESS FOR SINGLE SIDED USB.
- 3.HATCHED AREA IS PLACEMENT ZONE FOR LED,LED SHOULD BE CENTERED WITHIN ZONE,RECOMMEND 0805 PACKAGE

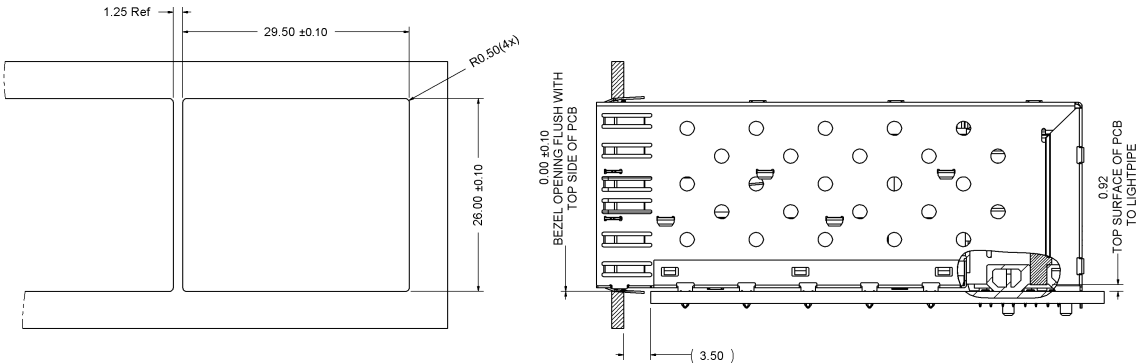
RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

PLATED THROUGH HOLE	1.05 SHIELD PINS	0.46 SIGNAL PINS
FINISHED HOLE DIAMETER	1.05±0.05	0.46±0.05
DRILLED HOLE DIAMETER	1.15	0.56
COPPER PLATING	0.025 min.	0.025 min.



RECOMMENDED MOTHER BOARD THROUGH HOLE DIMENSION

3. Recommended Panel cutout



PRESS-FIT ASSEMBLIES

Hand place using proper seating force to engage all Leg tails into plated thru-holes.

Assemblies are to be seated per the instructions associated with the appropriate insertion tool
Note:UDE recommends only one connector assembly be installed at a time.

ASSEMBLE INSERTION FORCE		
PORT SIZE	PCB FINISH	FORCE
2X2	Copper w/OSP	730±80N

4. Packing Information

- 12 pcs finished goods per tray
- 5 trays(60pcs finished goods) per master carton

5. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Terminal : Copper Alloy, Thickness=0.20mm

Finish : 30μ" min Gold Plating on contact area, 50μ" min. Nickel overall

Solder Tail : 30μ" min Matte Tin, 50μ" min Nickel overall

Top Shell : Copper Alloy, Thickness=0.25mm

Bottom Shell : Copper Alloy, Thickness=0.25mm

RL Mid Ground: Copper Alloy, Thickness=0.25mm

UD Mid Ground: Copper Alloy, Thickness=0.25mm

Inner Spring : SUS304, Thickness=0.20mm

Connector Housing: LCP, Black<UL94V-0>

Lightpipe Cover : PBT, Black<UL94V-0>

Light Pipe : PC, Transparent <UL94V-0>

6. Operating and Storage Temperature

Operating Temperature : -40°C to +85°C

Storage Temperature : -55°C to +105°C

7. SFP specifications

Contact Current Rating: 0.5A (per contact)

Insulation Resistance : 1000MΩ min.

Dielectric Withstanding Voltage : 300VDC @1min.

Insertion force : 40N MAX.

Extraction force : 12.5N MAX.

Durability : 100 cycles MIN.

Cage Retention (Latch strength) : 90N Min.

8. Performance and Test Description

Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

9. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.